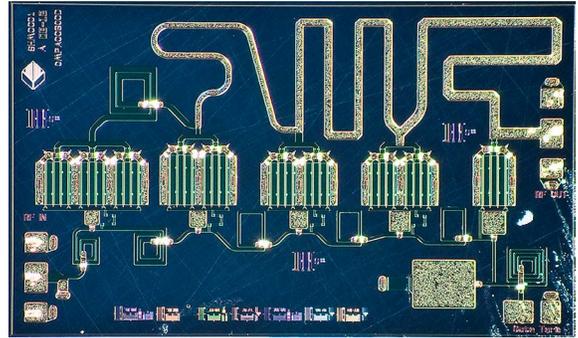


CMPA0060025D

25 W, 20 MHz - 6.0 GHz, GaN MMIC,
Power Amplifier

Description

The CMPA0060025D is a gallium nitride (GaN) High Electron Mobility Transistor (HEMT) based monolithic microwave integrated circuit (MMIC). GaN has superior properties compared to silicon or gallium arsenide, including higher breakdown voltage, higher saturated electron drift velocity and higher thermal conductivity. GaN HEMTs also offer greater power density and wider bandwidths compared to Si and GaAs transistors. This MMIC enables very wide bandwidths.



PN: CMPA0060025D

Typical Performance Over 1.0-6.0 GHz ($T_c = 25^\circ\text{C}$)

Parameter	1.0 GHz	2.0 GHz	3.0 GHz	4.0 GHz	5.0 GHz	6.0 GHz	Units
Gain	18.0	18.0	18.5	18.0	17.0	17.0	dB
Output Power @ P_{IN} 32 dBm	34	38	42	29	30	31	W
Associated Gain @ P_{IN} 32 dBm	13.3	13.9	14.2	12.6	13.1	12.9	dB
PAE @ P_{IN} 32 dBm	54	45	46	33	34	33	%

Note: $V_{DD} = 50$ V, $I_D = 500$ mA

Features

- 18 dB Small Signal Gain
- 30 W Typical P_{SAT}
- Operation up to 50 V
- High Breakdown Voltage
- High Temperature Operation
- Size 0.157 x 0.094 x 0.004 inches

Applications

- Ultra Broadband Amplifiers
- Test Instrumentation
- EMC Amplifier Drivers

Absolute Maximum Ratings (not simultaneous) at 25°C

Parameter	Symbol	Rating	Units	Conditions
Drain-source Voltage	V_{DSS}	84	V_{DC}	
Gate-source Voltage	V_{GS}	-10, +2		
Storage Temperature	T_{STG}	-65, +150	°C	
Operating Junction Temperature	T_J	225		
Maximum Forward Gate Current	I_{GMAX}	12	mA	
Thermal Resistance, Junction to Case (packaged) ¹	$R_{\theta JC}$	2.32	°C/W	85°C
Thermal Resistance (die only) ¹		1.40		
Input Power ²	P_{IN}	36	dBm	

Notes:

¹ Eutectic die attach using 80/20 AuSn solder mounted to a 10 mil thick CuMo carrier

² Limit for internal resistor only. Thermal dissipation may be exceeded at this level

Electrical Characteristics (Frequency = 20 MHz to 6.0 GHz unless otherwise stated; $T_c = 25^\circ\text{C}$)

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
DC Characteristics						
Gate Threshold Voltage ¹	$V_{GS(th)}$	-3.8	-3.0	-2.3	V	$V_{DS} = 20\text{ V}, \Delta I_D = 6\text{ mA}$
Gate Quiescent Voltage	$V_{GS(Q)}$	—	-2.7	—	V_{DC}	$V_{DD} = 50\text{ V}, I_{DQ} = 500\text{ mA}$
Saturated Drain Current ²	I_{DS}	—	12	—	A	$V_{DS} = 12.0\text{ V}, V_{GS} = 2.0\text{ V}$
RF Characteristics^{3,4}						
Small Signal Gain	S21	—	18	—	dB	$V_{DD} = 50\text{ V}, I_{DQ} = 500\text{ mA}$
Input Return Loss	S11	—	9	—		
Output Return Loss	S22	—	7	—		
Power Output at 4.0 GHz	P_{OUT}	17	29	—	W	$V_{DD} = 50\text{ V}, I_{DQ} = 500\text{ mA}, P_{IN} = 32\text{ dBm}$
Power Output at 5.0 GHz		23	30	—		
Power Output at 6.0 GHz		31	—	—		
Power Added Efficiency at 4.0 GHz	PAE	18	33	—	%	
Power Added Efficiency at 5.0 GHz		23	34	—		
Power Added Efficiency at 6.0 GHz		22	33	—		
Power Gain	G_P	—	13	—	dB	
Output Mismatch Stress	VSWR	—	—	5:1	Ψ	No damage at all phase angles, $V_{DD} = 50\text{ V}, I_{DQ} = 500\text{ mA}, P_{IN} = 32\text{ dBm}$

Notes:

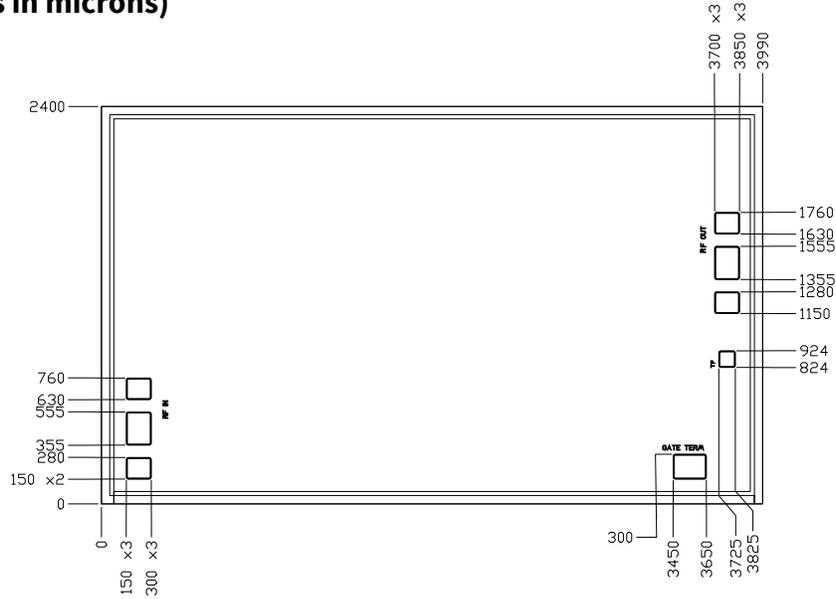
¹ The device will draw approximately 55-70 mA at pinch off due to the internal circuit structure

² Scaled from PCM data

³ All data pulsed with Pulse Width at 10 μs , 1% Duty Cycle

⁴ Data measured into a 15 dB output load with a maximum return loss

DIE Dimensions (units in microns)



Overall die size 3990 x 2400 (+0/-50) microns, die thickness 100 (+/-10) micron.
 All Gate and Drain pads must be wire bonded for electrical connection.

Pad Number	Function	Description	Pad Size (in)
1	RF IN ¹	RF-Input pad. Matched to 50 ohm. Requires gate control from an external bias -T from -2.3 V to -3.8 V.	150 x 200
2	Gate Termination	Off Chip termination for the Gate. It needs to be DC-blocked	200 x 150
3	Test Pad	Pad specific for probe	100 x 100
4	RF OUT ¹	RF-Output pad. Matched to 50 ohm. Requires Drain supply from an external bias -T up to 50 V , 2.0 A	150 x 200

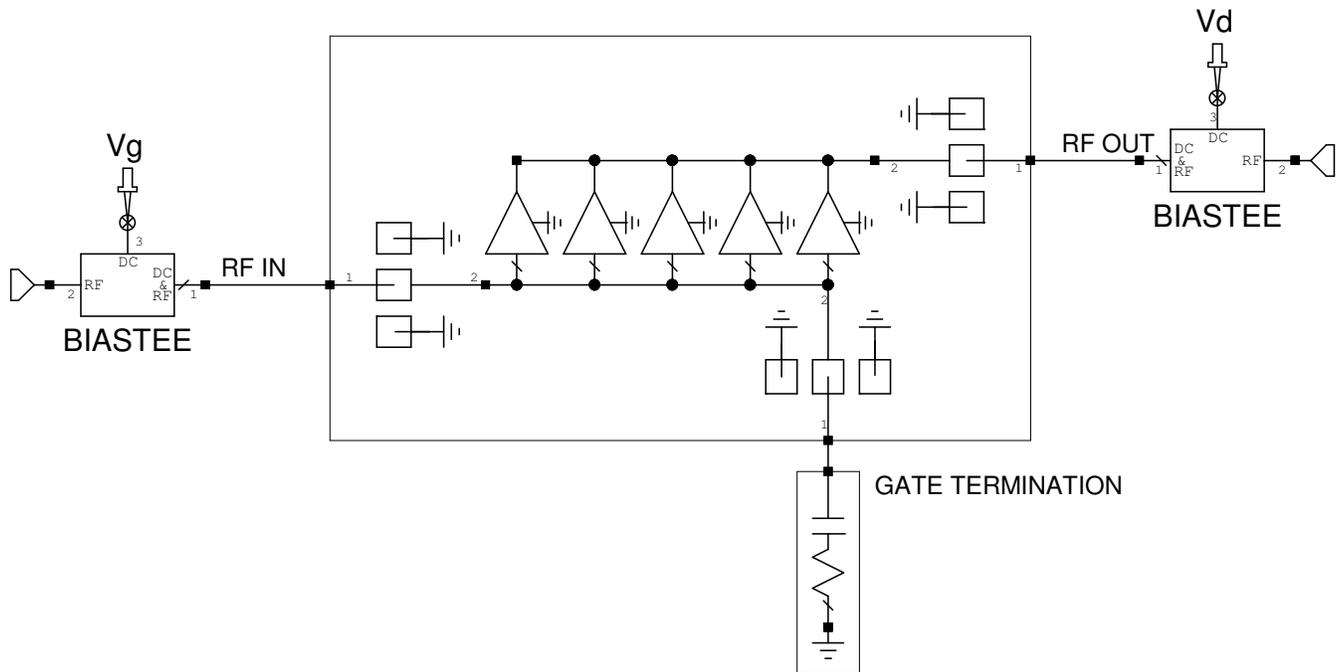
Note:
¹ The RF In and Out pads have a ground-signal-ground configuration with a pitch of 75 microns.

Die Assembly Notes

- Recommended solder is AuSn (80/20) solder. Refer to the website for the Eutectic Die Bond Procedure application note
- Vacuum collet is the preferred method of pick-up
- The backside of the die is the Source (ground) contact
- Die back side gold plating is 5 microns thick minimum
- Thermosonic ball or wedge bonding are the preferred connection methods
- Gold wire must be used for connections
- Test pad must be bonded to Ground
- Use the die label (XX-YY) for correct orientation

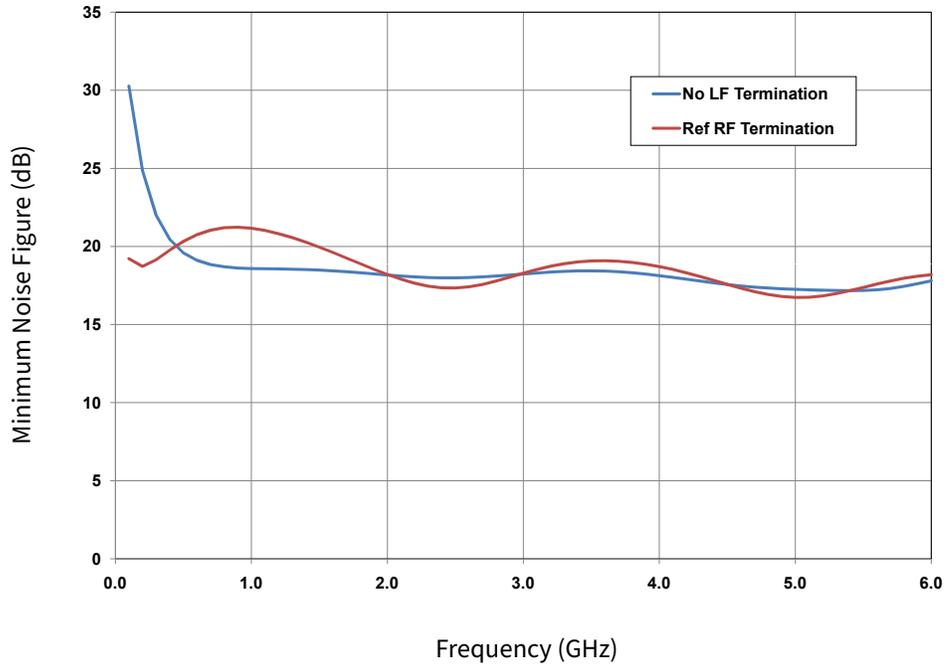
Functional Block Diagram

This device employs a wideband amplifier topology. It has an internal termination for the Gate, which works well over 1.0-6.0 GHz. For operation below 1.0 GHz an external termination is required. This termination needs to be DC-blocked and suitable to withstand up to 2 W of RF power. (Refer to the reference design section for the LF-termination in this data sheet for more details). The circuits also require external wideband Bias -T's to supply voltage to the Gate and Drain. The Bias-T at the Drain needs to be designed to handle 50 V and up to 2.0 A.



External Termination Reference Design

The following is a plot of the gain of the die with and without an RC reference circuit.

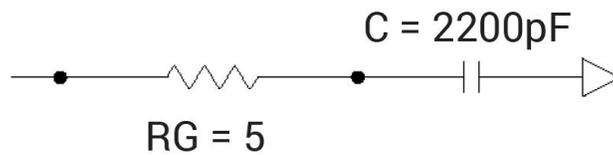


Notes:

- ¹ An off chip termination is needed to reduce the high gain peak at low frequencies
- ² The off chip termination should be designed to minimize the impact on the MMIC’s performance at higher frequencies

RC Reference Circuit

The reference circuit is a series capacitor and resistor as shown below. The resistor needs to handle 2.0 W.



Typical Performance

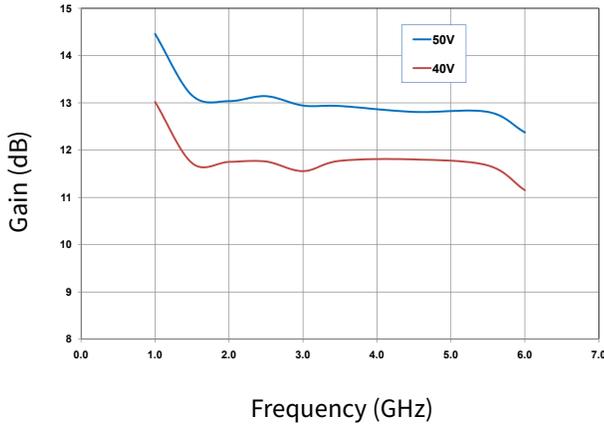


Figure 1. Power Gain vs Frequency
 $P_{IN} = 32 \text{ dBm}$

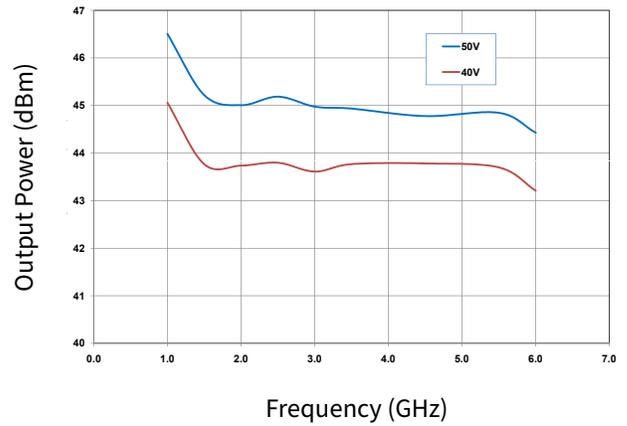


Figure 2. Power Output vs Frequency
 $P_{IN} = 32 \text{ dBm}$

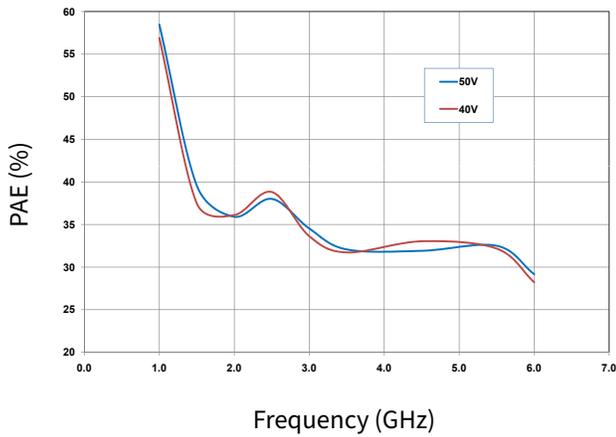


Figure 3. Power Added Efficiency vs Frequency
 $P_{IN} = 32 \text{ dBm}$

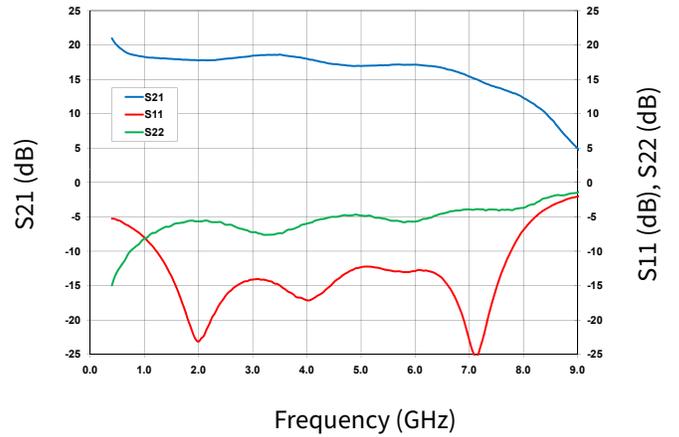
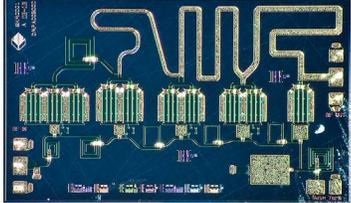


Figure 4. Gain and Return Losses vs Frequency
 $V_{DD} = 50 \text{ V}, I_{DQ} = 500 \text{ mA}$

Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Classification Level	Test Methodology
Human Body Model	HBM	TBD	ANSI/ESDA/JEDEC JS-001 Table 3	JEDEC JESD22 A114-D

Product Ordering Information

Order Number	Description	Unit of Measure	Image
CMPA0060025D	GaN MMIC Power Amplifier Bare Die	Each	

Notes & Disclaimer

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